

Jetting and Microdispensing Paste

Indium12.8HF

Versatile Paste for Various Systems

- Engineered to fit into a variety of jetting and microdispense systems
 - Flexible metal load (78–85%) to provide optimal dispensability
 - Fine-powder adaptability: Type 5, Type 5 MC, Type 6, Type 6 SG, Type 6 SGS, Type 7, Type 7 SGS
- Exceptional jetting and microdispensing performance for halogen-free and lead-free paste
 - Proven: Smooth, fast dispense; exceptional thermal stability, achieving consistent dot and line dispense without skips or clogging
- No-clean solder paste with **identical flux chemistry to Indium8.9HF Solder Paste**



Recommended
Type 6

**Proven:
Advanced
Performance**

Contact our engineers: askus@indium.com

Learn more: www.indium.com/ball-attach

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

Proven Microdispensing Solder Paste

Indium12.8HF

Versatile Paste for Various Systems

Specifically formulated for exceptional performance, **Indium12.8HF Solder Paste** is the most advanced jetting/microdispensing paste on the market.

Indium12.8HF achieved:

- Optimization for long-term dispensing
- Precise microdots as small as 80µm
- Consistent thinnest line deposit as narrow as 80µm



Scan for technical paper with supporting data.

Your Process and Material Experts:



Kenneth Thum

Senior Area Technical Manager

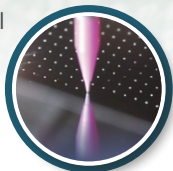
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Developed in collaboration with:

essemtec
A NANODIMENSION DIVISION

finetech

marco
PRECISION DISPENSING

VERMES
MICRODISPENSING

NSW
Automation

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